	CONNECTING CS INDUSTRIES INCONNECTING International and Part	PC, Bannockb	urn, Illinois. A	All rights reserved u ntions.	nder both	This docume level parts, t	ent is a declara he declaration	tion of th encompa	e substance sses all low	s within the er level mat	manufactur erials for wh	er listed it hich the m	tem. Note: i nanufacturer	if the item is an as r has engineering	sembly with low responsibility.
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					eous Materia	als and M	fg Informat	ion		
upplie	r Information														
Company name* Company unique ID				ique ID	Unique			Inique ID Authority				Response Date*			
nsemi												2024-06-02			
ontact N	Jame		Title - Contact			]	Phone - Contact*				Email - Contact*				
roduct-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative			]	Phone - Representative*				Email - Representative*				
roduct-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	e Versi	Version Manufacturing Site		1	Weight*	UOM	Unit Type	
	1N5821RLG REC SURM 3A 30			OV SCTKY TR	R	2024-06-02	-06-02 CNP			1	1334.62	mg	Each		
Ianufa	cturing Proccess Informat	tion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperate		ure Max Time at Peak Temp		Temperat	ure Numb	per of Reflow Cyc	eles		
Matte Tin (Sn) - annealed			U Alloy NA				0 C 30				seconds 3				
omments	8														
or more	information regarding material	composition	please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.67	mg	Supplier	Silicon (Si)	7440-21-3		6.67	mg
Die Attach Solder	46.69	mg	Supplier	Silver (Ag)	7440-22-4		1.1673	mg
			Α	Lead (Pb)	7439-92-1	7a	43.1882	mg
			Supplier	Tin (Sn)	7440-31-5		2.3345	mg
Lead Frame	731.48	mg	Supplier	Copper (Cu)	7440-50-8		731.48	mg
Mold Compound-Black	543.33	mg		Metal Hydroxide	proprietary data		27.1665	mg
			Supplier	Carbon Black (C)	1333-86-4		5.4333	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		407.4975	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		54.333	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		48.8997	mg
Plating	6.45	mg	Supplier	Tin (Sn)	7440-31-5		6.45	mg